

ABSTRACT**LOW DIELECTRIC GLASS AND FIBER
GLASS FOR ELECTRONIC APPLICATIONS**

Glass compositions are provided that are useful in electronic applications, e.g., as reinforcements in printed circuit board substrates. Reduced dielectric constants are provided relative to E-glass, and fiber forming properties are provided that are more commercially practical than D-glass. Glass compositions comprise (in weight%); SiO_2 60–68, Li_2O 0–2, B_2O_3 7–13 Na_2O 0–1, Al_2O_3 9–15 K_2O 0–1, MgO 8–15 Fe_2O_3 0–1, CaO 0–4 F_2 0–1, TiO_2 0–2, other constituents 0–5.